



## Product Brief

# SLJ 32P

## EMV payment solution based on SLE 77

Based on its unique expertise Infineon developed a family of advanced Java Card based payment solutions optimized for the EMV market. This portfolio reflects our commitment to innovating, enabling and simplifying the global migration to the EMV standard. Trusted by all major payment market players, our proven offering, covers the entire SDA, DDA/CDA and Dual Interface application spectrum based on a unique and high-running microcontroller family – the SLE 77.

### SLJ 32P includes

- > A high performance Java Card S operating system (Java Card 3.0.1) GlobalPlatform 2.2.1 compliant
- > The latest VSDC and M/Chip payment applets (SDA and DDA/CDA)
- > Package and inlay (optional) for Dual Interface solution
- > An advanced, 16-bit crypto-controller

### Facilitated and simplified payment scheme approval process

Infineon's solution enables regional players to participate in the growing EMV and Dual Interface market. To accelerate and simplify the approval process for card manufacturers, Infineon offers its payment solution with Visa and MasterCard approval reference. The product family is based on the SLE 77 SOLID FLASH™ with EMVCo certification.

Infineon's Dual Interface products will offer a pre-certified solution based on Coil on Module and a wired (PVC) inlay, which significantly will reduce development and approval costs and efforts.

### One-stop shop for payment products

Infineon offers the most comprehensive and proven payment product portfolio covering SDA, DDA to Dual Interface, as well as all contactless standards. Infineon also provides leading solutions for Transport Ticketing and Government ID, making us your partner of choice for all your Smart Card needs, present and future.

### Key features

- > Fast EMV Common Personalization (< 10 seconds per Visa/MasterCard initialization and personalization with standard profiles)
- > Full Visa approvals and MasterCard PIC (CAST and TAS)
- > VSDC and M/Chip (incl. Data Sharing Functionality) applets
- > Both applets pre-loaded on the same chip for contact solutions
- > High performance and field proven Java Card S (based on JC 3.0.1) compliant to GlobalPlatform 2.2.1 and EMV CPS 1.1
- > High-speed 16-bit processor
- > EMVCo approved SOLID FLASH™ SLE 77 chip family
- > SDA and DDA/CDA
- > Innovative Dual Interface technology (DIF)

### Customer key benefits

- > One-stop shop with Infineon, the recognized market and innovation leader for over 2 decades
- > Standardized and fast personalization
- > Customer can easily participate in Dual Interface market thanks to Coil on Module (CoM)
- > Lower tooling and manufacturing costs and highest manufacturing throughput for Dual Interface



SOLID FLASH™



Coil on Module



# SLJ 32P + Coil on Module

The most effective and versatile solution for dual interface

## Easy transition from contact-based to contactless with Coil on Module

Infineon's Coil on Module (CoM) technology for Dual Interface card production offers compelling benefits to our customers throughout the entire value chain. Unlike the conventional method which physically solders the chip to the antenna, CoM provides:

- › Compatibility with state-of-the-art wire embedded antenna technology
- › Use of universal card antenna for different Chip/Module combinations
- › High robustness, reliability and yield in card production and personalization
- › Simple manufacturing process compatible with contact-based
- › Up to 5x greater production throughput than the conventional method with direct antenna to module connection

## Product and ordering information

Sales code	SLJ 32PCD008A5	SLJ 32PCA016A5	SLJ 32PDA016A6	SLJ 32 PDA016A7
Target application	Entry level for SDA markets	Higher levels of fraud resistance (DDA)	Visa – Dual Interface	MasterCard – Dual Interface
Interface standard	T = 0 according to ISO/IEC 7816		T = CL (type A) according to ISO/IEC 14443 T = 0 according to ISO/IEC 7816	
Applets	VSDC2.8.1T M/Chip 4 Lite PSE applet	VSDC2.8.1F1 M/Chip 4 Select v1.1b PSE/PPSE applet	VSDC 2.8.1G PSE/PPSE	M/Chip Advance v1.1 <sup>1)</sup> PSE/PPSE
E <sup>2</sup> PROM/Available User NVM	8 kB	16 kB	16 kB	16 kB
Java Card S based on JC 3.0.1	Yes	Yes	Yes	Yes
GlobalPlatform 2.2.1 compliant	Yes	Yes	Yes	Yes
Package	Flip Chip 6-pin (MFC6.6) or 8-pin (MFC6.8), gold or palladium		Coil on Module 8-pin (COM8.6), gold or palladium Optional: Al etched (PET) or wired (PVC) inlay	

1) M/Chip applets include data sharing and pin sharing

For other SLJ 32P derivatives, further information on technology, delivery forms and conditions please contact your nearest Infineon Technologies sales representative:

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### Additional information

For further information on technologies, our products, the application of our products, delivery terms and conditions and/or prices, please contact your nearest Infineon Technologies office ([www.infineon.com](http://www.infineon.com)).

### Warnings

Due to technical requirements, our products may contain dangerous substances. For information on the types in question, please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by us in a written document signed by authorized representatives of Infineon Technologies, our products may not be used in any life-endangering applications, including but not limited to medical, nuclear, military, life-critical or any other applications where a failure of the product or any consequences of the use thereof can result in personal injury.